Overview

HP ZBook 15u G5 Mobile Workstation



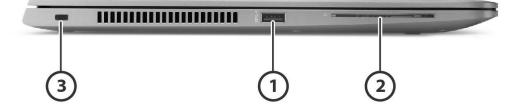
- 1. HD Camera (Select models only)
- 2. IR Camera (Select models only)
- 3. Webcam LED (Select models only)
- 4. Internal microphones
- 5. IR Camera LEDs (Select models only)
- 6. Power connector
- 7 USB Type-C[™] with Thunderbolt[™]
- 8. Docking connector
- 9. Ethernet port

- Front
 - 10. HDMI port (Cable not included)
 - 11. USB 3.1 Gen 1 port
 - 12. Audio combo jack
 - 13. SIM card slot¹
 - 14. Fingerprint sensor
 - 15. Clickpad
 - 16. Pointstick
 - 17. HP Collaboration Keyboard

¹All units have a SIM card slot and icon but units that do not support WWAN are shipped with a non-removable SIM slot plug



Overview



Left

- 1. 1 USB 3.0 (charging)
- 2. 1 smart card reader
- 3. Security lock slot



Overview

At A Glance

- Eye-catching ultraslim design, premium precision-crafted machined aluminum (CNC), seamless formed aluminum chassis for clean, crisp, premium look and feel Thin & light value performance industrial design,
- Tested and passed 14 MIL-STD-810G tests*.
- Workstation-caliber AMD Radeon Pro[™] discrete graphics: AMD Radeon Pro[™] WX3100 (2 GB dedicated GDDR5); AMD Enduro[™] graphics technology.
- Intel[®] Integrated graphics: Intel[®] HD Graphics 620 integrated on 7th Generation Intel Core processors. Intel[®] UHD Graphics 630 integrated on 8th Generation Intel Core processors.ISV certified to provide fast and reliable performance with workstation applications, including manipulation of 3D textures
- Choice of dual core 7th generation Intel[®] Core[™] i7 and i5 or quad core 8th generation Intel[®] Core[™] i7 and i5 processors
- Intel[®] Core[™] i7 with vPro[™] and Core[™] i5 with vPro[™] technology (optional)
- HP Performance Advisor for optimal configuration, compatibility and performance
- Up to two SODIMMs supporting up to 32 GB DDR4-2400 MHz dual channel memory. Supports up to 3 independent displays via internal LCD Panel, system DisplayPort[™], system VGA, or using the HP UltraSlim Docking Station or HP Thunderbolt Docking Station. Supports DisplayPort[™] 1.2 monitors.
- Featuring HP Collaboration Keyboard with Clickpad to manage most commonly used conferencing functions with a single keystroke. HP Spill Resistant Collaboration Keyboard with Durakeyswith Duracoat finish. Backlight keyboard in full aluminum deck with magnesium bottom reinforcement, chemically strengthened glass clickpad, and updated system functions indicators. One touch access: Wireless On/Off, Volume Mute
- HP tuned Bang and Olufsen audio optimized for high fidelity audio with immersive surround sound with deep, rich bass and crystal-clear dialog without distortion at high volume, and new discrete amp.
- Up to 14 hours of battery life using an HP Long life battery solution: 3-cell (56 WHr) supporting HP Fast Charge Technology
 - 15.6-inch diagonal LED-backlit display: FHD IPS eDP anti-glare, 67% sRGB at 220 nits (1920x1080)
 - FHD IPS eDP + PSR anti-glare, 100% sRGB at 400 nits with ambient light sensor (1920x1080)
 - UHD IPS eDP + PSR anti-glare, 100% sRGB at 400 nits with ambient light sensor (3480x 2160)
 - FHD IPS eDP touch screen with Corning Gorilla Glass 3, 67% sRGB at 220 nits (1920x1080)
 - HP SureView Integrated Privacy Display FHD IPS eDP + PSR anti-glare 100% sRGB at 650 nits (1920x1080)
- Wireless connectivity options:
 - o Intel[®] Dual Band Wireless-AC 8265 802.11 AC (2x2) WiFi and Bluetooth 4.2 combo adaptor (vPro™)
 - o Intel[®] Dual Band Wireless-AC 8265 802.11 AC (2x2) WiFi and Bluetooth 4.2 combo adaptor (non-vPro™)
 - o Realtek RTL8822BE 802.11ac 2x2 Wi-Fi and Bluetooth 4.2 combo adapter
 - Optional integrated wireless 4G (LTE) mobile broadband module support
- One dedicated drive slot. (1) M.2 slots support up to 2 TB of storageEnterprise grade security with HP SureStart Gen4, HP Privacy Camera³, HP Sure View², HP Sure Run, HP Sure Recover, and Fingerprint sensor² Low halogen, ENERGY STAR[®] certified and EPEAT[®] Gold registered in the U.S. EPEAT[®] status varies by country- please see epeat.net.

* MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective features sections.



Features

OPERATING SYSTEM

Preinstalled OS	Windows 10 Pro 64*
	Windows 10 Home Plus 64*

FreeDOS 2.0

Supported OS Windows 10 Enterprise 64*

* Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com

NOTE: Your product does not support Windows 8 or Windows 7 In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel and AMD 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com

PROCESSOR*

7th Generation Intel[®] Core™ i7-7600U with Intel[®] HD Graphics 620 (2.8 GHz base frequency, up to 3.9 GHz with Intel[®] Turbo Boost Technology, 4 MB cache, 2 cores)

7th Generation Intel[®] Core™ i7-7500U with Intel[®] HD Graphics 620 (2.7 GHz base frequency, up to 3.5 GHz with Intel[®] Turbo Boost Technology, 4 MB cache, 2 cores)

7th Generation Intel[®] Core[™] i5 7300U vPro[™] with Intel[®] HD 620 graphics (2.6 GHz, 3 MB cache, 2 cores) * Up to 3.5 GHz with Intel[®] Turbo Boost Technology

7th Generation Intel[®] Core[™] i5 7200U with Intel[®] HD 620 graphics (2.5 GHz, 3 MB cache, 2 cores) * Up to 3.1 GHz with Intel[®] Turbo Boost Technology

8th Generation Intel[®] Core™ i7 8650U vPro™ with Intel[®] UHD 630 graphics (1.9 GHz, 8 MB cache, 4 cores) * Up to 4.2 GHz with Intel[®] Turbo Boost Technology

8th Generation Intel[®] Core[™] i7 8550U with Intel[®] UHD 630 graphics (1.8 GHz, 8 MB cache, 4 cores) * Up to 4.0 GHz with Intel[®] Turbo Boost Technology

8th Generation Intel[®] Core™ i5 8350U vPro™ with Intel[®] HD 620 graphics (1.7 GHz, 6 MB cache, 4 cores) * Up to 3.6 GHz with Intel[®] Turbo Boost Technology

8th Generation Intel[®] Core[™] i5 8250U with Intel[®] UHD 630 graphics (1.6 GHz, 6 MB cache, 4 cores) * Up to 3.4 GHz with Intel[®] Turbo Boost Technology

* Multi-Core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

Also note that the Intel[®] Turbo Boost is based on max GHz for a single core.



Features

CHIPSET

Intel[®] Kaby Lake Chipset integrated with 7th Generation processor Intel[®] Kaby Lake – R Chipset integrated with 8th Generation processor

INTEL® CORE™ I5 WITH VPRO/CORE I7 WITH VPRO TECHNOLOGY CAPABLE

Intel[®] Core[™] i5 with vPro[™] and Core[™] i7 with vPro[™] technology is a selectable feature that is available on units configured with select processors, a qualified Intel[®] WLAN module and a preinstalled Windows operating system. It provides advances in remote manageability, security, energy efficient performance, and wireless connectivity. Intel Active Management Technology (iAMT) offers built-in manageability and proactive security for networked mobile workstations, even when they are powered off* or when the operating system is inoperable. It can help identify threats before they reach the network, isolate infected systems, and update mobile workstations regardless of their power state.

* Requires a Windows operating system, network hardware and software, connection with a power source, and a direct (non-VPN) corporate network connection which is either cable or wireless LAN.

NOTE: Some functionality of Intel[®] Core[™] i5 with vPro[™]/Core[™] i7 with vPro[™] technology, such as Intel Active Management technology and Intel Virtualization technology, requires additional third- party software in order to run. Availability of future "virtual appliances" applications for Intel[®] Core[™] i5 with vPro[™]/Core[™] i7 with vPro[™] technology is dependent on third- party software providers. Compatibility with future "virtual appliances" is yet to be determined.

GRAPHICS

Intel® HD 620 Graphics* Intel® UHD 630 Graphics** AMD Radeon Pro™ WX3100 (2 GB dedicated GDDR5) ** Microsoft DirectX 12 (Shader Model 5.0) and OpenGL 4.3capable AMD Enduro™ Technology supported.

* HD content required to view HD images; only available on 7Th Generation Intel[®] processors

** UHD content required to view UHD images; only available on 8th Generation Intel[®] processors

** Supports up to 3 independent displays via internal LCD Panel, system HDMI 1.4, or using the HP UltraSlim Docking Station DisplayPort™ and VGA ports (sold separately).

DISPLAY

Internal

- 15.6" diagonal FHD IPS eDP anti-glare, 67% sRGB at 220 nits (1920x1080)
- 15.6" diagonal FHD IPS eDP + PSR anti-glare, 100% sRGB at 400 nits with ambient light sensor (1920x1080)
- 15.6" diagonal UHD IPS eDP + PSR anti-glare, 100% sRGB at 400 nits with ambient light sensor (3480x 2160)
- 15.6" diagonal FHD IPS eDP touch screen with Corning Gorilla Glass 3, 67% sRGB at 220 nits (1920x1080)
- HP SureView Integrated Privacy Display 15.6" diagonal FHD IPS eDP + PSR anti-glare 100% sRGB at 650 nits (1920x1080)

External

Up to 30-bit (2^30) per pixel "Deep Color" (total of 1,073,741,824 color variations)



Features

HDMI 1.4b

Supports resolution up to 4k @ 24 Hz

Without HP Thunderbolt Dock G2:

HP ZBook 15u with hybrid graphics and without the use of a dock supports up to a maximum of three independent displays. These three displays are the internal panel plus two external displays connected two of the three following ports: HDMI 1.4, Thunderbolt[™] 3. HP ZBook 15u configuration with Intel[®] integrated graphics and without the use of a dock supports up to a maximum of three independent displays. Any three-display combination of the system panel plus 2 of the following HDMI, Thunderbolt[™] 3.

With HP UltraSlim Dock G2:

Supports up to 2 independent displays when docked on the HP Ultraslim Dock - Max. resolution = 2.5K @ 60Hz (DP1) & 2.5K @ 60Hz (DP2)11

With HP Thunderbolt Dock G2:

The HP Thunderbolt Dock G2 has Thunderbolt[™] 3 port, VGA, two DisplayPort[™] 1.3, and a USB-C port. When used together with the HP ZBook 15u configuration with hybrid graphics, a maximum of three independent displays are supported. These three displays are internal panel and two external displays connected to the ZBook dock's Thunderbolt[™] 3, VGA, or two DisplayPort[™] ports. When used together with the HP ZBook 15u configuration with Intel[®] integrated graphics, a maximum of three independent displays are supported. Any three-display combination of the system panel, system ports and ZBook Dock ports. Max. resolution = 4K @60Hz (DP1) & 4K @60Hz (DP2) with Thunderbolt

NOTE: Resolutions are dependent upon monitor capability, and resolution and color depth settings.

STORAGE AND DRIVES

One (1) dedicated M.2 drive slots, supporting up to 2 TB of storage

M.2 SATA Solid State Drive:

128 GB SATA Solid State Drive 512 GB SATA TLC FIPS-140-2 Solid State Drive

HP Z Turbo Drive (NVMe PCIe SSD): 256 GB PCIe (NVMe) TLC Solid State Drive 512 GB PCIe (NVMe) TLC Solid State Drive 1 TB PCIe (NVMe) TLC Solid State Drive 2 TB PCIe (NVMe) TLC Solid State Drive 256 GB PCIe (NVMe) TLC Self Encrypting (SED) Solid State Drive 512 GB PCIe (NVMe) MLC Solid State Drive 256 GB PCIe (NVMe) MLC Solid State Drive 512 GB PCIe (NVMe) MLC Solid State Drive 512 GB PCIe (NVMe) MLC Solid State Drive 1 TB PCIe (NVMe) MLC Solid State Drive

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to up to 30 GB (for Windows 10) disk is reserved for system recovery software.

DRIVE CONTROLLERS



Features

M.2 Storage Bay (SATA): HP Z Turbo Drive: RAID: SATA-3 for Solid State Drive PCIe Gen 3 x 4 lanes NVMe Solid State Drive Not supported

MEMORY

Standard

Up to 32 GB DDR4 1.2V Non ECC SDRAM Transfer rates up to 2133MT/s on Intel Kaby Lake Chipset or Transfer rates up to 2400MT/s on Intel Kaby Lake – R Chipset Two SODIMM slots supporting dual-channel memory 4 GB, 8GB and 16 GB SODIMMs

Maximum

Upgradeable to 32768 MB with optional 16384 MB SODIMMs in 2 slots

Dual-channel

Maximized dual-channel performance requires SODIMMs of the same size and speed in both memory channels.

* Maximum memory capacities assume Windows 64-bit operating systems or Linux. With Windows 32-bit operating systems, memory above 3 GB may not all be available due to system resource requirements.

NOTE: Due to the non-industry standard nature of some third-party memory modules, we recommend HP branded memory to ensure compatibility. If you mix memory speeds, the system will perform at the lower memory speed.

NETWORKING/COMMUNICATIONS

Communications

Intel® I219-LM Gigabit* Network Connection (vPro configurations) Intel® I219-V Gigabit* Network Connection (non-vPro configurations)

* The term "10/100/1000" or "Gigabit" Ethernet indicates compatibility with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/s. For high-speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required.

Wireless

Secure, integrated wireless LAN and wireless WAN options featuring support for the latest industry standards. Broadband Wireless (WWAN) requires a Windows operating system and is available in select countries as a standard, factory configurable feature only. Integrated Bluetooth is also available (factory configurable only) combined with the supported wireless LAN option.

802.11 Wireless LAN*

Intel® Dual Band Wireless-AC 8265 802.11 AC (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (vPro) Intel® Dual Band Wireless-AC 8265 802.11 AC (2x2) WiFi + Bluetooth 4.2 Combo Adaptor* (non-vPro) Realtek RTL8822BE 802.11 ac (2x2) WiFi + Bluetooth 4.2 Combo Adapter*

Wireless WAN - Mobile Broadband **

Intel XMM 7360 LTE-Advanced Broadband Module (optional) HP It4132, LTE/HSPA+ 4G Mobile Broadband Module (optional)



Features

Miracast***

Native Miracast Support

Near Field Communications (NFC)

NXP NPC300 Near Field Communication Module (optional)

* Wireless cards are optional or add-on features and requires separately purchased wireless access point and internet service. Availability of public wireless access points limited. The specifications for the 802.11ac WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the notebook to communicate with other 802.11ac WLAN devices.

** WWAN use requires separately purchased service contract. Check with service provider for coverage and availability in your area. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products, and in all regions.

*** Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming

AUDIO/MULTIMEDIA

Audio

Audio custom tuned by HP and Bang and Olufsen audio Integrated stereo speakers Integrated HP World Facing microphone (dual-microphone array when equipped with optional webcam) Button for volume mute; function keys for volume up and down Combo mic-in / stereo headphone-out jack

Webcam

720 HD webcam

720 HD webcam with infrared (IR) imaging (optional)

- Microsoft Hello Certification: Microsoft face authentication in Windows 10 is an enterprise-grade identity verification
 mechanism
- Microsoft Skype for Business1 Certified
- HD format (widescreen 16:9)
- Supports videoconferencing and still image capture
- High quality fixed focus lens
- Video capture at various resolutions up to 1280x720 resolution (720p) and up to 30fps
- · M-JPEG compression supports higher frame rates for video capture and videoconferencing
- Improved low light sensitivity
- Improved dynamic range

HP Privacy Camera Shutter (only available on non-touch configurations)

* HD content required to view HD images.



Features

KEYBOARDS/POINTING DEVICES/BUTTONS & FUNCTION KEYS

Keyboard

Optional backlit HP Collaboration keyboard with Function key control to toggle backlit brightness setting - off/full/half brightness. The HP spill-resistant keyboard is designed using a thin layer of Mylar film under the keyboard and a drain system that funnels fluid through a hole in the bottom of the notebook. This minimizes the risk of damage to sensitive components underneath. The 102-key compatible keyboard features a full-pitch key layout with desktop keyboard features, such as editing keys, both left and right control and alt keys, function keys, and 18.0 x 18.4 mm key pitch (center-to-center spacing). U.S. and International key layouts are available. Other features include hot keys for instant access to power conservation and brightness.

Pointing Devices

Clickpad with multi-touch gestures enabled, taps enabled as default Microsoft Precision Touchpad Default Gestures Support Dual Point Stick

Function Keys

Function keys provide control of the following features: standby mode, external display, volume down, volume up HP Power Assistant (Windows[®] 7 only), and display brightness.

F1 - Display Switching

- F2 Blank or SureView
- F3 Brightness Down
- F4 Brightness Up
- F5 Audio Mute
- F6 Volume Down
- F7 Volume Up
- F8 Mic Mute
- F9 Blank or Backlit Toggle
- F10 Numlk
- F11 Wireless
- F12 Calendar
- >Share/Present
- >Call Answer
- Call End

Hidden Fuctions

Fn+R = Break Fn+S = Sys Rq Fn+C = Scroll Lock

SOFTWARE AND SECURITY

Preinstalled Software with Windows Operating System

BIOS

HP BIOSphere Gen4¹ HP DriveLock | HP Automatic DriveLock BIOS Update via Network Master Boot Record Security Power On Authentication Secure Erase³ Absolute Persistence Module⁴



Features

Pre-boot Authentication HP Wireless Wakeup

Multi Media

Cyberlink Power MediaPlayer CMIT

Communication / Connectivity

HP Mobile Connect Pro⁵ Native Miracast Support⁶ HP LAN-WLAN Protection HP MAC Address Manager (select models only) HP Wireless Wakeup (select models only) HP SureConnect HP Noise Cancellation Software

HP Value Add Software

HP 3D DriveGuard 6 HP ePrint Driver + JetAdvantage⁷ HP Hotkey Support HP Recovery Manager HP Jumpstart HP Support Assistant¹² HP Performance Advisor HP Remote Graphics Software HP Velocity

Microsoft Products

Buy Office Bing Search Skype⁸

Manageability

HP Driver Packs⁹ HP SoftPaq Download Manager (SDM) HP System Software Manager (SSM)⁹ HP BIOS Config Utility (BCU)⁹ HP Client Catalog⁹ HP Manageability Integration Kit Gen 2 for Microsoft SCCM¹⁰ HP Image Assistant LANDESK Management¹¹

For more information on HP Client Management Solutions refer to: http://www.hp.com/go/clientmanagement.

Client Security Software

- HP Client Security Suite Gen4¹³
- HP Security Manager (including Credential Manager Password Manager and HP Spare Key)
- HP Fingerprint Sensor
- Power On Authentication
- Device Access Manager
- Microsoft Defender ¹⁴
- HP WorkWise¹⁵

Standard

HP BIOSphere Gen4 ²³ HP DriveLock & Automatic DriveLock



Features

BIOS Update via Network Secure Erase²⁴ **Pre-boot Authentication** TPM 2.0 Embedded Security Chip shipped with Windows 10 (Common Criteria EAL4+ Certified)³⁷ SATA 0.1 port disablement (viaBIOS) RAID configurations³⁷ Serial, USB enable/disable (viaBIOS) Power-on password (viaBIOS) Setup password (viaBIOS) Support for chassis padlocks and cable lock devices HP Sure Click³⁸ HP Sure Start Gen4³⁵ HP Sure Run³⁹ HP Sure Recover⁴⁰

TPM

Model: Infineon SLB9670 Version: 7.63.3353.0 Revision: TPM 2.0 FIPS 140-2 Compliant: Yes (select models only)

IPv6 Certification:

Yes

MD5 Hash:

Please follow the instructions below to access MD5 Hash.

Log-on to http://hp.com/support, enter your product name, select software and drivers, select OS, select driver. After selecting

the driver, click on "Associated files" and then click on "Download". When opening the file, under "Purpose" you should see the

appropriate "SOFTPAQ MD5:" Field

Is the BIOS on this notebook ISO/IEC 19678:2015 (formerly NIST 800-147) compliant?

Yes

UEFI version: 2.5

HP Fingerprint Sensor

For more information on HP Client Security Software Suite, refer to http://www.hp.com/go/clientsecurity.

1.Requires Intel[®] 7th generation processors or greater

2. Available on HP Elite and Z products equipped with Intel® 7th generation processors or greater

3.For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88. Supported on Elite and Z platforms with BIOS version F.03 or higher

4. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit:

http://www.absolute.com/company/legal/agreements/ computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software. 5.HP Mobile Connect Pro is only available on preconfigured devices with WWAN. For geographic availability refer to

http://www.hp.com/go/mobileconnect

6. Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming media players that also support Miracast. You can use Miracast to share what you're doing on your PC and present a slide show. For more information: http://windows.microsoft.com/en-us/windows-8/project-wireless-screen-miracast

7.Requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see http://www.hp.com/go/eprintcenter). Separately purchased data plans or usage fees may apply. Print times and connection speeds may vary.

8.Skype is not offered in China.



HP ZBook 15u G5 Mobile Workstation

QuickSpecs

Features

9.Not preinstalled, however available for download at http://www.hp.com/go/clientmanagement

10.HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html 11.Subscription required.

12.Requires Windows and Internet Access

13.Requires Windows and Intel[®] 7th generation processors.

14.0pt in and internet connection required for updates.

15.HP WorkWise smartphone app is available as a free download on the App Store and Google Play. As of September 2017, HP WorkWise will no longer support iOS or iPhone[®] devices.

Miracast is a wireless technology your PC can use to project your screen to TVs, projectors, and streaming

23. HP BIOSphere Gen4 features may vary depending on the PC platform and configurations requires 8th Gen Intel[®] processors.

24. Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88. Supported on Elite platforms with BIOS version F.03 or higher.

25. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

26. HP ePrint Driver requires an Internet connection to HP web-enabled printer and HP ePrint account registration (for a list of eligible printers, supported documents and image types and other HP ePrint details, see

http://www.hp.com/go/eprintcenter). Print times and connection speeds may vary.

27. HP Support Assistant requires Windows and Internet access.

28. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

29. HP Manageability Integration Kit can be downloaded from

http://www8.hp.com/us/en/ads/clientmanagement/overview.html

30. Ivanti Management Suite subscription required.

31. HP Client Security Suite Gen4 requires Windows and Intel® or AMD 8th generation processors.

32. HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.

33. Microsoft Defender Opt in and internet connection required for updates.

34. HP PhoneWise Client is only available on select platforms. For supported platforms and HP PhoneWise system

requirements see http://www.hp.com/go/HPPhoneWise.

35. HP Sure Start Gen4 is available on HP EliteBook products equipped with Intel® 8th generation processors

36. HP Fingerprint Sensor sold separately or as an optional feature.

37. RAID configuration is optional and does require a second hard drive.

38. HP Sure Click is available on select HP platforms and supports Microsoft[®] Internet Explorer and Chromium[™]. Check http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=4AA7-0922ENW for all compatible platforms as they become

available.

39. HP Sure Run is available on HP Elite products equipped with Intel® or AMD® 8th generation processors

40. HP Sure Recover is available on HP Elite PCs with 8th generation Intel® or AMD processors and requires an open, wired network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data

Workstation ISV Certifications

Find the latest list of certifications at: http://www.hp.com/go/isv

HP Remote Graphics Software

The remote desktop solution for serious workstation users and their most demanding applications. Download at: http://www.hp.com/go/RGS

HP Performance Advisor

Get the most out of your HP Workstation on day one—and every day thereafter. Designed for all users regardless of technical background, this ultra-savvy software wizard is the simplest and most effective way to make sure your computer is always operating at its optimum potential.

Download at: http://www.hp.com/go/performanceadvisor



Features

Security

See Software section above.

Other Standard Security Features

Integrated Smart Card Reader One-Step Logon Security lock slot Support for Intel[®] AT

Optional Security Features

HP Fingerprint Sensor (optional)

Absolute Data Protect* with GPS Tracking - Subscription based security solution providing the ability to track, initiate physical recovery, conduct asset management, and perform remote data delete by utilizing GPS technology. GPS functionality requires HP Mobile Broadband Module.

* The Absolute Data Protect agent is shipped turned off, and must be activated by customers when they purchase a subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S.

HP CENTRAL MANAGEMENT

HP offers a variety of scalable hardware, software, and BIOS-based security features to help you defend your organization against viruses and other threats. These integrated security features safeguard what matters to you the most - your data, device and identity. Now, be confident your fleet of devices is protected in multiple layers of HP Client Security protection.

HP BIOS Protection keeps you up and running with enhanced protection against virus attacks and other threats. And if the BIOS is accidently compromised, the auto recovery feature automatically restores it to its fully functional state.

HP Sure Start detects and negates a BIOS attack with automatic recovery of the BIOS even when the installation is accidentally compromised (i.e. power outage). When HP Sure Start heals the BIOS an event log is generated that an IT administrator can retrieve so the business is aware of a BIOS attack. Golden copy of BIOS is stored in protected nonvolatile memory providing redundant, hardware-based protection against a new generation of attacks.

An optional fingerprint reader and integrated Smart Card Reader help keep your identity secure. The security cable slot helps keep your notebook physically secure.

You can even permanently destroy data on your hard drive in preparation for your system disposal or redeployment with Secure Erase.



Features

POWER

Power Supply

HP Smart 45 W External AC power adapter⁴² HP Smart 45 W External AC power adapter, 2-prong (Japan only)⁴² HP Smart 65 W External AC power adapter⁴² HP Smart 65 W EM External AC power adapter⁴² 45 W USB Type-C[™] adapter⁴² 65 W USB Type-C[™] adapter⁴² HP 65W Slim Smart AC Adapter

Primary Battery HP Long Life 3-cell Lithium Polymer Battery (56 WHr) supporting HP Fast Charge Technology

Power Cord

2-wire plug - 1.0m (Japan only)⁴² 3-wire plug - 1.0m⁴² 3-wire plug - 1.8m⁴² Duckhead power cord - 1.0m⁴²

Duckhead power cord - 1.8m⁴²

Battery Life

Battery life up to 14 hours *

System Standby Time

Up to 1 week**

*Battery life will vary depending on the product model, configuration, loaded applications, features, use, wireless functionality and power management settings. The maximum capacity of the battery will naturally decrease with time and usage. See MobileMark14 battery benchmark https://bapco.com/products/mobilemark-2014/ for additional details. ** Standby life will vary depending on various factors including battery, Memory, CPU, EC and LAN chip. The maximum capacity of the battery will naturally decrease with time and usage.

Power Conservation

AMD[®] Polaris™ Technology Hibernation Standby ACPI compliance

ENVIRONMENTAL

US ENERGY STAR[®] IT ECO declaration EPEAT[®] Gold; registered where applicable. EPEAT[®] registration varies by country. See <u>http://www.epeat.net</u> for registration status by country. See HP's 3rd party option store for solar energy accessory www.hp.com/go/options.

NOTE: This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks.

WEIGHTS & DIMENSIONS



Features

Weight

Non-Touch starting at 3.89 lb (1.77 kg) 4.25 lb (1.93 kg) Touch starting at

Dimensions (w x d x h) Non-Touch 14.6 x 9.91 x 0.72 in 370.8 x 251 x 18.25 mm

Touch 14.6 x 9.91 x 0.73 in 370.8 x 251 x 18.6 mm

NOTE: Height varies depending upon where on the notebook the measurement is made. Weight varies by configuration and components. Weight includes 3 cell 56Whr battery, without hard drive and with 256 GB Z Turbo Drive (PCIe SSD).

PORTS/SLOTS

Ports

Left side:

(1) USB 3.0 Charging Port (1) Security lock slot

Right side:

(1) Thunderbolt 3[™] (1) USB 3.0 Port (1) Headphone/Microphone Combo (1) RJ-45 / Ethernet (1) Side Docking connector (1) Power connector (1) SIM Card Slot

Digital Media Slots

(1) Integrated Smart Card Reader (Compatible with ISO 7816 compliant Smart Cards PC/SC interface support)

SERVICE AND SUPPORT

Limited 3-year or 1-year limited warranty options available, depending on country. Batteries have the same 1-year or 3-year limited warranty as the platform. Optional¹ HP Care Pack Services are extended service contracts which go beyond your standard limited warranties. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at http://www.hp.com/go/cpc.

Sold separately or as an optional feature. Service levels and response times for HP Care Packs may vary depending 1. on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product. Consult your local HP Customer Support Center for details.



Technical Specifications – System Unit

SYSTEM UNIT

Stand-Alone Power Requirements (AC Power)	Nominal Operating Voltage	19.5 V dc @ 3.3 A
	Average Operating	Windows® 10 (64-bit)
	Power	AMD FirePro™ Graphics
	Max Operating Power	< 45 W with UMA < 65 W with discrete
Temperature	Operating	32° to 95° F (0° to 35° C) (not writing optical) 41° to 95° F (5° to 35° C) (writing optical)
	Non-operating	-4° to 140° F (-20° to 60° C)
Relative Humidity	Operating	10% to 90%, non-condensing
	Non-operating	5% to 95%, 101.6° F (38.7° C) maximum wet bulb temperature
Shock	Operating	40 G, 2 ms, half-sine
	Non-operating	200 G, 2 ms, half-sine
Random Vibration	Operating	0.75 grms
	Non-operating	1.50 grms
Altitude (unpressurized)	Operating	-50 to 10,000 ft. (-15.24 to 3,048 m)
	Non-operating	-50 to 15,000 ft. (-15.24 to 12,192 m)
Planned Industry	UL	Yes
Standard Certifications	CSA	Yes
Certifications	FCC Compliance	Yes
	ENERGY STAR®	Select models*
	EPEAT [®]	Gold **
	ICES	Yes
	Australia / NZ A-Tick Compliance	Yes
	כככ	Yes
	Japan VCCI Compliance	Yes
	KCC	Yes
	BSMI	Yes
	CE Marking Compliance	Yes
	MIL STD***	Passed 14 Mil STD Tests

* Configurations of the HP ZBook 15u G5 that are ENERGY STAR[®] certified are identified as HP ZBook 15u G5 ENERGY STAR[®] on HP websites and on http://www.energystar.gov.

** EPEAT registration varies by country. See http://www.epeat.net for registration status by country.

EPEAT status listed above applies to U.S.

*** MIL STD 810G testing is pending and is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Damage under the MIL STD test conditions or any accidental damage requires an optional HP Accidental Damage Protection Care Pack.

For accessibility information on HP products, please visit: http://www.hp.com/accessibility.



Technical Specifications – Displays

DISPLAYS

DISPLATS			
15.6" diagonal LED backlit FHD IPS eDP anti-	Outline Dimensions (W × H)	350.96 x 216.75 (max.)	
glare, 67% sRGB at 220	Active Area	344.16 x 193.59 (typ.)	
nits (1920x1080)	Weight	370g max.	
	Diagonal Size	15.6 inch	
	Thickness	3.2mm max.	
	Interface	eDP 1.2	
	Panel Technology	IPS	
	Surface Treatment	Anti-glare	
	Touch enabled	No	
	Contrast Ratio	600:1 (typ.) - AG	
	Refresh Rate	60Hz	
	Brightness	220 nits typical (panel only))
	Pixel Resolution	Format	1920 x 1080 (FHD)
		Configuration	RGB
	Backlight	LED	
	Color Gamut Coverage	67% sRGB	
	Color Depth	6 bits + Hi FRC	
	Viewing Angle	UWVA 85/85/85/85	
15.6" diagonal LED Backlit FHD IPS eDP +	Outline Dimensions (W x H)	350.96 x 216.75 (max.)	
PSR anti-glare, 100% sRGB at 400 nits with	Active Area	344.16 x 193.59 (typ.)	
ambient light sensor	Weight	370g max.	
(1920x1080)	Diagonal Size	15.6 inch	
	Thickness	3.2mm max.	
	Interface	eDP 1.3 + PSR (2 lane)	
	Panel Technology	IPS	
	Surface Treatment	Anti-Glare (AG)	
	Touch Enabled	No	
	Contrast Ratio	600:1 (typical)	
	Refresh Rate	60Hz	
	Brightness	400 nits typical (panel only	y)
		Format	1920 x 1080 (FHD)
	Pixel Resolution	Configuration	RGB
	Backlight	LED	
	Color Gamut Coverage	100% sRGB	
	Color Depth	6 bits + Hi FRC	
	PPI	157	
	Viewing Angle	UWVA 85/85/85/85	
	5 5		

Technical Specifications – Displays

15.6" diagonal UHD IPS eDP + PSR anti-glare,	Outline Dimensions (W × H)	350.96 x 216.95 (max.)	
100% sRGB at 400 nits with ambient light sensor (3840x 2160)	Active Area	344.21 x 193.62 (typ.)	
	Weight	320g max.	
	Diagonal Size	15.6"	
	Thickness	2.6mm (max.)	
	Interface	eDP 1.3 + PSR	
	Panel Technology	IPS	
	Surface Treatment	AG	
	Contrast Ratio	1200:1 (typ.)	
	Touch Enabled	No	
	Refresh Rate	60Hz	
	Brightness	400 nits typical (panel onl	y)
		Format	3280 x 2160 (UHD)
	Pixel Resolution	Configuration	RGB
	Backlight	LED	
	Color Gamut Coverage	100% sRGB	
	Color Depth	8 bit	
	Viewing Angle	UWVA 85/85/85/85	
15.6" diagonal FHD IPS eDP touch screen with	Outline Dimensions (W x H)	350.96 x 216.75 (max.)	
Corning Gorilla Glass 3,	Active Area (W × H)	344.16 x 193.59 (typ.)	
67% sRGB at 220 nits (1920x1080)	Weight	568g (max.)	
(1920/1000)	Diagonal Size	15.6 inch	
	Thickness	3.4mm (max.)	
	Interface	eDP 1.2	
	Panel Technology	IPS	
	Touch enabled	Yes with Corning Gorilla G	ass 3
	Contrast Ratio	600:1 (typ.)	
	Refresh Rate	60Hz	-)
	Brightness Pixel Resolution	220 nits typical (panel onl	y) 1920 x 1080 (FHD)
	Pixel Resolution	Format Configuration	
		Configuration	RGB
	Backlight	Configuration LED	
	Backlight Color Gamut Coverage	Configuration LED 67% sRGB	
	Backlight	Configuration LED	

Technical Specifications – Displays

HP SureView Integrated Privacy Display 15.6"	Outline Dimensions (W x H)	350.96 x 216.75 (max.)	
diagonal FHD IPS eDP +	Active Area (W × H)	344.46 x 193.89 (typ.)	
PSR anti-glare 100% sRGB at 650 nits	Weight	320g (max.)	
(1920x1080)	Diagonal Size	15.6 inch	
• • • • • • •	Thickness	2.80mm (max.)	
	Interface	eDP 1.4 + PSR	
	Panel Technology	IPS	
	Surface Treatment	AG	
	Touch enabled	No	
	Contrast Ratio	Sharing mode, 600:1 (typ. Privacy mode, 150:1 (typ.	
	Refresh Rate	120Hz	
	Brightness	Sharing mode, 650 nits (ty Privacy mode, 350 nits (ty	
	Pixel Resolution	Format	1920 x 1080 (FHD)
		Configuration	RGB
	Backlight	LED	
	Color Gamut Coverage	100% sRGB	
	Color Depth	8 bits	
	Viewing Angle	Sharing mode, CR > 10 L/F Privacy mode, CR > 2 L/R/	

Technical Specifications – Storage

STORAGE AND DRIVES*

JI UNAUL AND DRIV			
128 GB M.2 SATA TLC	Drive Weight	0.02 lb (10g)	
Solid State Drive	Capacity	128 GB	
	Height	0.09 in (2.3mm)	
	Width	0.87 in (22mm)	
	Interface	ATA-8, SATA 3.0	
	NAND Type	TLC	
	Form Factor I/O	M.2 2280	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 520 MB/s	Up to 450 MB/s
	Logical Blocks	250,069,680	
	Operating Temperature	32 to 158F (0 to 70C) [ambie	ent temp]
	Features	DIPM; TRIM; DEVSLP	
HP Z Turbo Drive 512 GB,	Drive Weight	0.02 lb (10 g)	
M.2 SATA TLC FIPS Solid	Capacity	512 GB	
State Drive	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	ACS-3, SATA 3.2	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 530 MB/s	Up to 400 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [am	nbient temp]
	Features	ATA Security; TCG Opal 2.0; F	FIPS; DIPM; TRIM; DEVSLP
HP Z Turbo Drive 1 TB,	Drive Weight	0.02 lb (10 g)	
M.2 NVMe MLC Solid	Capacity	1024 GB	
State Drive	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	MLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Drive Weight	0.02 lb (10 g)	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 3,000 MB/s	Up to 2,900 MB/s
	Logical Blocks	2,000,409,264	
	Operating Temperature	32° to 158°F (0° to 70°C) [an	nbient temp]
	Features	ATA Security (Option), TRIM;	L1.2
HP Z Turbo Drive 512 GB,	Drive Weight	0.022 lb (10 g)	
M.2 NVMe MLC Solid	Capacity	512 GB	
State Drive	Height	0.09 in (2.3 mm)	

Technical Specifications – Storage

	Width NAND Type Form-Factor (I/O) Interface Performance	0.87 in (22 mm) MLC M.2 2280 PCIe NVMe Gen3X4 Maximum Sequential Read	Maximum Sequential Write
		Up to 3000 MB/s	Up to 1500MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [am	bient temp]
	Features	ATA Security (option), TRIM;	L1.2
HP Z Turbo Drive 256 GB,	-	0.02 lb (10 g)	
M.2 NVMe MLC Solid State Drive	Capacity	256 GB	
State Brive	Height	0.09 in (2.23 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	MLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 3,100 MB/s	Up to 1,400 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [am	bient temp]
	Features	ATA Security (Option);TRIM; I	_1.2
HP Z Turbo Drive 2 TB,	Drive Weight	0.02 lb (10 g)	
M.2 NVMe TLC Solid State Drive	Capacity	2 TB	
DINC	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		2,900 MB/s	2,100 MB/s
	Logical Blocks	3,907,029,168	•
	Operating Temperature	32° to 158°F (0° to 70°C) [am	bient temp]
	Features	ATA Security; DIPM; TRIM; DE	•



Technical Specifications – Storage

HP Z Turbo Drive 1 TB,	Drive Weight	0.02 lb (10g)	
M.2 NVMe TLC Solid State Drive	Capacity	1 TB	
	Height	0.09 in (2.3mm)	
	Width	0.87 in (22mm)	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
	Performance	Up to 2800 MB/s	Up to 1600 MB/s
	Logical Blocks	2,000,409,264	
	Operating Temperature	32 to 158F (0 to 70C) [ambie	nt temp]
	Features	TRIM; L1.2	
HP Z Turbo Drive 512 GB,		0.02 lb (10g)	
M.2 NVMe TLC Solid State	Capacity	512 GB	
Drive	Height	0.09 in (2.3mm)	
	Width	0.87 in (22mm)	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 2600 MB/s	Up to 1400 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32 to 158F (0 to 70C) [ambie	nt temp]
	Features	TRIM; L1.2	
HP Z Turbo Drive 256 GB.	Drive Weight	0.02 lb (10 g)	
M.2 NVMe TLC Solid State	Canacity	256 GB	
Drive	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to2,600 MB/s	Up to 900 MB/s
	Logical Blocks	500,118,192	
	Operating Temperature	32° to 158°F (0° to 70°C) [am	bient temp]
	Features	ATA Security (Option); TRIM;	•

Technical Specifications – Storage

HP Z Turbo Drive 512 GB,	Drive Weight	0.02 lb (10 g)	
M.2 NVMe Self Encrypting	Capacity	512 GB	
TLC Solid State Drive	Height	0.09 in (2.3 mm)	
	Width	0.87 in (22 mm)	
	NAND Type	TLC	
	Form-Factor (I/O)	M.2 2280	
	Interface	PCIe NVMe Gen3X4	
	Performance	Maximum Sequential Read	Maximum Sequential Write
		Up to 2,600 MB/s	Up to 1,400 MB/s
	Logical Blocks	1,000,215,216	
	Operating Temperature	32° to 158°F (0° to 70°C) [am	bient temp]
	Features	ATA Security (Option); TRIM;	OPAL 2, L1.2
HP Z Turbo Drive 256 GB,	•	0.02 lb (<10g)	
M.2 NVMe Self-	Drive Weight Capacity	0.02 lb (< l0g) 256 GB	
•	•	5	23mm)
M.2 NVMe Self- Encrypting TLC Solid	Capacity	256 GB	23mm)
M.2 NVMe Self- Encrypting TLC Solid	Capacity Height	256 GB 0.14 in (3.58mm)- 0.09 in (2.	23mm)
M.2 NVMe Self- Encrypting TLC Solid	Capacity Height Width	256 GB 0.14 in (3.58mm)- 0.09 in (2. 0.87 in (22mm)	23mm)
M.2 NVMe Self- Encrypting TLC Solid	Capacity Height Width NAND Type	256 GB 0.14 in (3.58mm)- 0.09 in (2. 0.87 in (22mm) TLC	23mm)
M.2 NVMe Self- Encrypting TLC Solid	Capacity Height Width NAND Type Form-Factor (I/O)	256 GB 0.14 in (3.58mm)- 0.09 in (2. 0.87 in (22mm) TLC M.2 2280	
M.2 NVMe Self- Encrypting TLC Solid	Capacity Height Width NAND Type Form-Factor (I/O) Interface	256 GB 0.14 in (3.58mm)- 0.09 in (2. 0.87 in (22mm) TLC M.2 2280 PCIe NVMe Gen3X4	
M.2 NVMe Self- Encrypting TLC Solid	Capacity Height Width NAND Type Form-Factor (I/O) Interface	256 GB 0.14 in (3.58mm)- 0.09 in (2. 0.87 in (22mm) TLC M.2 2280 PCIe NVMe Gen3X4 Maximum Sequential Read	Maximum Sequential Write
M.2 NVMe Self- Encrypting TLC Solid	Capacity Height Width NAND Type Form-Factor (I/O) Interface Performance	256 GB 0.14 in (3.58mm)- 0.09 in (2. 0.87 in (22mm) TLC M.2 2280 PCIe NVMe Gen3X4 Maximum Sequential Read Up to 530 MB/s	Maximum Sequential Write Up to 515 MB/s
M.2 NVMe Self- Encrypting TLC Solid	Capacity Height Width NAND Type Form-Factor (I/O) Interface Performance	256 GB 0.14 in (3.58mm)- 0.09 in (2. 0.87 in (22mm) TLC M.2 2280 PCIe NVMe Gen3X4 Maximum Sequential Read Up to 530 MB/s 500,118,192	Maximum Sequential Write Up to 515 MB/s nt temp]

* For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to up to 30 GB (for Windows 10) disk is reserved for system recovery software.



Technical Specifications – Networking

SECURITY

HP Fingerprint Sensor	Voltage	3.0-3.6V
	Operating temperature	14° - 167°F (-10° - 75°C)
	Current consumption image	36mA
	Low latency wait for finger	950 uA
	Capture rate	3000 lines/sec
	ESD Resistance	IEC 6100-4-2 4B (+/-15KV)
	Detection Matrix	200*1 (plus another secondary line); 508 dpi, sensor area 12*3 mm
Smart Card Reader	Smart card standard	PC/SC 2.0 for Windows smart card standard
	Dimensions (L x W x H)	0.41 x 0.08 x 0.32 in (10.5 x 2 x 8.2 mm)
	Smart Card support	ISO 7816 Class A and AB smart cards
	Smart Card Interface	Smart Card Interface with T = 0 and T = 1 support Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT88SC1608, AT45D041 card and AT45DB041 card via external EEPROM
	Operating systems	Normal Mode With card present, before being suspended: 40.9 mA Without card present, before being suspended: 33.16 mA After being suspended with smart card present: 380 µA After being suspended without smart card present: 380 µA
	Features	 Power Saving Mode: With card present, before being suspended: 40.6 mA Without card present: 380 µA After being suspended with smart card present: 380 µA Support single slot Support T0, T1 protocol Support I2C memory card, SLE4418, SLE4428, SLE4432, SLE4442, SLE4436, SLE5536, SLE6636, AT885C1608, AT45D041 card and AT45DB041 card via external EEPROM Support ISO7816 Class A, B and C (5V/3V/1.8V) card Implemented as an USB full speed device with bulk transfer endpoint, Mass Storage endpoint Built-in PLL for USB and Smart Card clocks requirement Support EEPROM for USB descriptors customization (PID/VID/ iManufacturer/iProduct/Serial Number), Direct Web Page Link, and accessing memory card module. EEPROM programmable via USB interface Support Direct Web Page Link via configuration in external EEPROM Support Software update for memory card module Support Software update for Module Support Software update for memory card module Support
		Normal/PWR Saving Mode) • Support card power over current protection mechanism • Built in resonator. • Support USB LPM (Link Power Management) features. • Embedded clock source.

NETWORKING/COMMUNICATION



Intel® I219-LM Gigabit Network Connection (vPro configurations)	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13- 14) 100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023. Clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3az EEE(Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection
	Power	ACPI compliant - multiple power modes
	Management	Energy Detect Low Power Mode(Green Ethernet)
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload(ARP & NS) Large send offload and Giant send offload Receiving Side Scaling MACSec Offload (802.3ae) Intel® vPro iSCSI Boot RSS is kernel based support (e.g. in Win Server 2013) Ultra Low Power at cable disconnect (<1mW) enables platform support for connected standby.
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ. NOTE: Intel [®] I219-LM Gigabit interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.
	NIC Device Driver Name	Intel [®] Ethernet Network Connection I219-LM

Intel® I219-V Gigabit Network Connection (Non-vPro configurations)	Ethernet Features	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14) 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30) 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023. Clauses 40) Auto-Negotiation (Automatic Speed Selection) Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s IEEE 802.1p QoS (Quality of Service) Support IEEE 802.1q VLAN support IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable) IEEE 802.3az EEE(Energy Efficient Ethernet) Jumbo Frame 9K Auto MDI/MDIX Crossover cable detection
	Power Management	ACPI compliant - multiple power modes Energy Detect Low Power Mode(Green Ethernet)
	Performance Features	TCP/IP/UDP Checksum Offload (configurable) Protocol Offload(ARP & NS) Large send offload and Giant send offload Receiving Side Scaling MACSec Offload (802.3ae) Intel Non-vPro iSCSI Boot
	Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite Virtual Cable Doctor for Ethernet cable status
	Interface	PCI Express 1.1 x1 to fully support ASPM LOs/L1 and CLKREQ. NOTE: Intel 82579 PCIe interface is not PCIe compliant. It operates at half of PCIe specification V1.1 (2.5GT/S) speed.
	NIC Device Driver Name	Intel 82579LM/82579V Ethernet Network Connection



HP lt4132 LTE/HSPA+ 4G Mobile Broadband Module

··· · · · ·	
Technology/Operating bands	LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3) MHz, 850 (Band 5), 2600 (Band 7), 900 (Band 8) MHz, 800 (Band 20), 700 (Band 28) MHz. HSPA+: 2100 (Band 1), 1900 (Band 2), 850 (Band 5), 900 (Band 8) MHz E-GPRS: 1900 (Band 2), 1800 (Band 3), 850 (Band 5), 900 (Band 8) MHz
Wireless protocol standards	3GPP Release 10 LTE Specification CAT.4, 20MHz BW WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification E-GPRS: Class B, Multi-slot class 12, coding schemes CS1 - CS4 and MSC1 - MSC9
GPS	Standalone, A-GPS (MS-B and LTO)
GPS bands	1575.42 MHz ± 1.023 MHz, GLONASS 1596-1607MHz
Maximum data rates	LTE: 150 Mbps (Download), 50 Mbps (Upload) DC-HSPA+: 42 Mbps (Download), 5.76 Mbps (Upload) HSPA+: 21Mbps (Download), 5.76 Mbps (Upload) EDGE: 236.8 kbps (Download), 236.8 kbps (Upload) GPRS: 85.6 kbps(Download), 85.6 kbps (Upload)
Maximum output power	LTE: 23 dBm HSPA+: 23.5 dBm E-GPRS 1900/1800: 26 dBm E-GPRS 900/850: 27 dBm GPRS 1900/1800: 29.5 dBm GPRS 900/850: 32.5 dBm
Maximum power consumption	LTE: 1,200 mA (peak); 900 mA (average) HSPA+: 1,100 mA (peak); 800 mA (average) E-GPRS: 2,600 mA (peak); 500 mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	6 g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3 mm

* Mobile Broadband is an optional feature. Connection requires wireless data service contract, network support, and is not available in all areas. Contact service provider to determine the coverage area and availability. Connection speeds will vary due to location, environment, network conditions, and other factors. 4G LTE not available on all products or in all countries.

Intel XMM 7360 LTE-Advanced Mobile Broadband Module

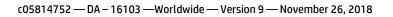
Technology/Operating bands	FDD LTE: 2100 (Band 1), 1900 (Band 2), 1800 (Band 3), 1700/2100 (Band 4), 850 (Band 5), 2600 (Band 7), 900 (Band 8), 1400 (Band 11), 700 (Band 12 lower), 700 (Band 13 upper), 700 (Band 17 lower), 850 (Band 18 lower), 850 (Band 19 upper), 800 (Band 20), 1400 (Band 21), 850 (Band 26), 700 (Band 28), 700 (Band 29 RX only), 2300 (Band 30), 2100 (Band 66). TDD LTE: 2600 (Band 38), 1900 (Band 39), 2400 (Band 40), 2500 (Band 41). HSPA+: 2100 (Band 1), 1900 (Band 2), 1700/2100 (Band 4), 850(Band 5), 900 (Band 8)
Wireless protocol standards	3GPP Release 11 LTE Specification CAT.9, DL 60 MHz BW throughput up to 450Mbps; UL 20MHz throughput up to 50Mbps WCDMA R99, 3GPP Release 5, 6, 7 and 8 UMTS Specification
GPS	Standalone A-GPS (MS-A, MS-B and XTRA)
GPS bands	1575.42MHz +/- 1.023MHz, GLONASS 1596-1606MHz, Beidou 1561.098MHz



Technical Specifications – Networking

Maximum output power	LTE: 23dBm HSPA+: 23dBm
Maximum power consumption	LTE: 1,200mA (peak); 900mA (average) HSPA+: 1,100mA (peak); 800mA (average)
Form Factor	M.2, 3042-S3 Key B
Weight	5.8g
Dimensions (Length x Width x Thickness)	42 x 30 x 2.3mm

Thickness)			
Intel® Dual Band Wireless-AC 8265 802.11 AC/a/b/g/n (2x2) WiFi + Bluetooth® 4.2 Combo Adaptor* (vPro)	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11n IEEE 802.11n	
	Interoperability	Wi-Fi certified	
	Frequency Band	802.11b/g/n	2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels
		802.11a	4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)
	Data Rates	 802.11b: 1, 2, 802.11g: 6, 9, 802.11n: MCS 	12, 18, 24, 36, 48, 54 Mbps 5.5, 11 Mbps 12, 18, 24, 36, 48, 54 Mbps 0 ~ MCS 15, (20MHz, and 40MHz) 50 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and
	Modulation	Direct Sequence Sprea CCK, BPSK, QPSK, 16-	ad Spectrum QAM, 64-QAM, 256-QAM
	Security ¹	a/b/g mode of AES-CCMP: 1 802.1x author WPA, WPA2: WPA2 certific IEEE 802.11i Cisco Certific CCX Lite WAPI	28 bit in hardware entication 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. cation d Extensions, all versions through CCX4 and
	Network Architecture	Ad-hoc (Peer to Peer)	
	Models	Infrastructure (Access	-
	Roaming	IEEE 802.11 complian	t roaming between band Access Points





Technical Specifications – Networking Output Power² 802.11b : +16dBm minimum 802.11g: +14dBm minimum • 802.11a : +14dBm minimum • 802.11n HT20(2.4GHz) : +13dBm minimum . 802.11n HT40(2.4GHz): +13dBm minimum . 802.11n HT20(5GHz) : +12dBm minimum 802.11n HT40(5GHz): +12dBm minimum **Power Consumption** Transmit: 2.0 Watts (max) Receive: 1.6 Watts (max) Idle mode (PSP): 180 mW (WLAN Associated) Idle mode: 50 mW (WLAN unassociated) Connect Standby: 10mW (WLAN + BT) Radio disabled: 5 mW ACPI and PCI Express compliant power management **Power Management** 802.11 compliant power saving mode 802.11b, 1Mbps : -94dBm maximum **Receiver Sensitivity³** 802.11b, 11Mbps : -86dBm maximum 802.11g, 6Mbps : -88dBm maximum 802.11g, 54Mbps : -74dBm maximum 802.11a, 6Mbps : -88dBm maximum 802.11a, 54Mbps : -74dBm maximum 802.11n, MCS07 : -69dBm maximum 802.11n, MCS15 : -66dBm maximum 802.11ac, 1SS, MCS-0: -86dBm maximum 802.11ac, 1SS, MCS-9: -61dBm maximum 802.11ac, 2SS, MCS-0 : -83dBm maximum 802.11ac, 2SS, MCS-9: -58dBm maximum Antenna Type High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO and Bluetooth communications **Form Factor** PCI-Express M.2 MiniCard Dimensions Type 2230 : 2.3 x 22.0 x 30.0 mm 0r Type 1630 : 2.3 x 16.0 x 30.0 mm Weight Type 2230 : 2.8g Or Type 1630 : 2g **Operating Voltage** 3.3v +/- 9% Temperature 14° to 158° F (-10° to 70° C) Operating Non-operating -40° to 176° F (-40° to 80° C) Humidity Operating 10% to 90% (non-condensing) Non-operating 5% to 95% (non-condensing) Altitude **Operating Non-**0 to 10,000 ft (3,048 m) operating 0 to 50,000 ft (15,240 m) **LED** Activity LED Amber - Radio OFF; LED White - Radio ON



Intel® Dual Band Wireless-AC 8265 802.11 AC/a/b/g/n (2x2) WiFi + Bluetooth® 4.2 Combo Adaptor* (non-vPro)	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac
	Interoperability	Wi-Fi certified
	Frequency Band	802.11b/g/n
		2.402 - 2.482 GHz Note: The FCC has declared as of January 1, 2015 products that utilize passive scanning on channel 12/13 and are capable of transmitting must fully comply with requirements of 15.247 or otherwise disable those channels
		802.11a
		 4.9 - 4.95 GHz (Japan) 5.15 - 5.25 GHz 5.25 - 5.35 GHz 5.47 - 5.725 GHz 5.825 - 5.850 GHz Note: Indonesia only supports 5.725 - 5.825 GHz (CH149 - CH161)
	Antenna Structure	2 transmit; 2 receive (2x2)
	Data Rates	802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11b: 1, 2, 5.5, 11 Mbps 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps 802.11n: card will support rates for NSS=1 and NSS=2 for RX and TX for 20 and 40 MHz channels. Short and long guard interval shall be supported. 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, and 80MHz)
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM
	Security ¹	 IEEE and Wi-Fi compliant 64 / 128 bit WEP encryption for a/b/g mode only AES-CCMP: 128 bit in hardware 802.1x authentication WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification IEEE 802.11i Cisco Certified Extensions, all versions through CCX4 and CCX Lite WAPI
	Network Architecture Models	Ad-hoc (Peer to Peer) Infrastructure (Access Point Required)
	Roaming	IEEE 802.11 compliant roaming between access points
	Output Power ²	 802.11b : +16dBm minimum 802.11g : +14dBm minimum 802.11a : +14dBm minimum



	 802.11n H 802.11n H 802.11n H 802.11n H 	T2O(2.4GHz) : +13dBm minimum T4O(2.4GHz) : +13dBm minimum T2O(5GHz) : +12dBm minimum T4O(5GHz) : +12dBm minimum OMHz(5GHz) : +11dBm minimum		
Power Consumption	Transmit: 2.0 W (ma Receive: 1.6 W (max Idle mode (PSP): 18 Idle mode: 60 mW (\ Radio disabled: 30 n	:) 0 mW (WLAN Associated) NLAN unassociated)		
Power Management	ACPI and PCI Expres 802.11 compliant p	s compliant power management ower saving mode		
Receiver Sensitivity ³	85 dBm (18 Mbps), -	802.11g:-90 dBm (6 Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), - 85 dBm (18 Mbps), -82 dBm (24 Mbps), -79 dBm (36 Mbps), -76 dBm (48 Mbps), -74 dBm (54 Mbps)		
	802.11b:-95 dBm (1 88 dBm (11 Mbps)	Mbps), -93 dBm (2 Mbps), -91 dBm (5.5 Mbps), -		
		i Mbps), -89 dBm (9 Mbps), -87 dBm (12 Mbps), - ·82 dBm (24 Mbps), -79 dBm (36 Mbps), -76 dBm (54 Mbps)		
	802.11n:-69 dBm (1	50 Mbps), -66 dBm (300 Mbps)		
Antenna type	display enclosure Two embedded dua	nna with spatial diversity, mounted in the l band 2.4/5 GHz antennas are provided to the IN MIMO communications and Bluetooth		
Form Factor		niCard		
Dimensions	PCI-Express Half-Mi	in (3.4 x 26.8 x 30 mm)		
Weight	3.1g			
Operating Voltage	3.3v +/- 9%			
Temperature	Operating Non-operating	14° to 158° F (-10° to 70° C) -40° to 176° F (-40° to 80° C)		
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)		
Altitude	Operating Non-operating	0 to 10,000 ft. (3,048 m) 0 to 50,000 ft. (15,240 m)		
LED Activity	LED Amber - Radio (DFF; LED White - Radio ON		
1. Check latest software/driver release for updates on supported security features.				

 2. Maximum output power may vary by country according to local regulations.
 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).



Realtek RTL8822BE 802.11ac 2x2 Wi-Fi + BT4.2 Combo Adapter	Wireless LAN Standards	IEEE 802.11a IEEE 802.11b IEEE 802.11g IEEE 802.11n IEEE 802.11ac			
	Interoperability	Wi-Fi certified			
	Frequency Band	802.11b/g/n			
		• 2.402 – 2.482 GHz			
		Note:			
		The FCC has declare utilize passive scan of transmitting mus 15.247 or otherwise	ning on chan st fully compl	nel 12/13 and ly with requir	l are capable
		802.11a/n			
		• 4.9 – 4.95 GHz (Jap	an)		
		• 5.15 – 5.25 GHz			
		• 5.25 – 5.35 GHz			
		• 5.47 – 5.725 GHz			
		• 5.825 – 5.850 GHz			
	Data Rates	Note: Indonesia no sup		d)	
	Dala Kales	 802.11b: 1, 2, 5.5, 1 802.11g: 6, 9, 12, 18 	-	54 Mbpc	
		 802.11g. 6, 9, 12, 18 802.11a: 6, 9, 12, 18 		-	
		 802.11n: MCS 0 ~ M 			<u>z</u>)
		802.11ac : MCS0 ~ MCS9, (1) 80MHz)			
	Modulation	Direct Sequence Spread Spectrum BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM			
	Security ¹	 IEEE and WiFi comp 	liant 64 / 12	8 bit WEP end	ryption for
		a/b/g mode only			
		• AES-CCMP: 128 bit			
		802.1x authenticat			
		 WPA, WPA2: 802.1 WPA2 certification 	x. wpa-psk,	WPAZ-PSK, I	KIP, and AES.
		 WPA2 Certification IEEE 802.11i 			
		Cisco Certified Exte	nsions. all ve	ersions throu	th CCX4 and
		CCX Lite			,
		• WAPI			
	Network Architecture	Ad-hoc (Peer to Peer) Infrastructure (Access Point	Poquired)		
	Models Roaming	IEEE 802.11 compliant roam	•	access point	c
	Output Power ²		-	-	
		TX Power(dBm)	Min	Typical	Max
		802.11b	+14	+15.5	
		802.11g	+12	+13.5	



	802.11a		+12	+13.5	
	802.11n HT2	0(2.4GHz)	+12	+13.5	
	802.11n HT4	0(2.4GHz)	+12	+13.5	
	802.11n HT2	0(5GHz)	+10	+11.5	
	802.11n HT4	0(5GHz)	+10	+11.5	
	802.11ac VH	T80(5GHz)	+10	+11.5	
Power Consumption	Transmit: 2.0 W	(max)			
	Receive: 1.6 W (r	-			
	Idle mode (PSP):	·		d)	
	Idle mode: 50 m	-	-		
	Connect Standby Radio disabled: 8		N+BI)		
Power Management	ACPI and PCI Exp		nower man	adoment	
r ower Frankgement	802.11 compliar	•	•	lagement	
Receiver Sensitivity ³	RX Sensitivity	(dBm)	Min	Typical	Max
	802.11b, 1Mbr			-95	-93.5
	802.11b, 11Mt			-85.5	-84
	802.11a/g, 6M	-		-87.5	-86
	802.11a/g, 54Mbps			-73.5	-72
	802.11n, MCS07			-68.5	-67
	802.11n, MCS1			-65.5	-64
	802.11ac, MCS			-85.5	-84
	802.11ac, MCS			-60.5	-59
Antenna type		High efficiency antenna with spatial diversity, mounted in the			
	display enclosure			in the	
Two embedded dual band 2.4/5 GHz antennas are provided					
	card to support WLAN MIMO communications and Bluetooth communications				
Form Factor	PCI-Express M.2 MiniCard				
Dimensions	Type 2230 : 2.3 x 22.0 x 30.0 mm				
	Or				
	Type 1630 : 2.3 >		m		
Weight	Type 2230 : 2.8g Or	I			
	Type 1630 : 2g				
Operating Voltage	3.3v +/- 9%				
Temperature	Operating	14° to 158° F (
	Non-operating	40° to 176° F (-	
Humidity	Operating Non-operating	10% to 90% (r 5% to 95% (no			
Altitude	Operating	0 to 10,000 ft		iliy)	
הנוונטעב	Non-operating	0 to 50,000 ft			
WoWLAN	Support S3/S4 both AC and DC mode				
LED Activity	LED Amber – Radio OFF; LED White – Radio ON				
-					



- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CKK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

HP Integrated Module with Blue	tooth 4.2 Wireless T	echnology		
Bluetooth Specification	4.2 Compliant			
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	Legacy : 0~79 (1 MH	z/CH)		
	BLE : 0~39 (2 MHz/C	H)		
Data Rates and Throughput	Legacy : 3 Mbps data	a rate; throughput ı	up to 2.17 Mbps	
	BLE : 1 Mbps data ra	te; throughput up t	o 0.2 Mbps	
	Legacy : Synchronou voice channels	is Connection Orien	ted links up to 3, 64 k	kbps,
	Legacy : Asynchrono kbps asymmetric (3-		s links 2178.1 kbps/1 Symmetric (3-EV5)	77.1
Transmit Power			e as a Class I Bluetoot ^r of + 4 dBm for BR an	
Receiver Sensitivity	Modulation	0.01% BER	0.001% BER	
	GFSK	-80 dBm	-70 dBm	
	π/4-DQPSK	-80 dBm	-70 dBm	
	8DPSK	-80 dBm	-70 dBm	
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW			
Range	Up to 33 ft (10 m)			
Electrical Interface	USB 2.0 compliant			
Bluetooth Software Supported	•	Bluetooth Software		
Link Topology				
Electrical Interface	Point to Point, Multip	point Pico Nets up t	o 7 slaves	
Bluetooth Software Supported Security	Full support of Bluet	ooth Security Prov	isions	
Power Management	Microsoft Windows A	ACPI, and USB Bus S	Support	
Certifications	Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff			
Security	All necessary regulatory approvals for supported countries, including:			
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249			
Bluetooth Profiles Supported				
Power Management	ETS 300 328, ETS 300 826			
Certifications	Low Voltage Directiv	ve IEC950		
Certifications	UL, CSA, and CE Mark	UL, CSA, and CE Mark		
Bluetooth Profiles Supported	Serial Port Profile (S	PP) ^{1.2}		
	Service Discovery Ap	oplication Profile (S	DAP)	



		Dial-Up Network Generic Object Ex Object Push Prof Hard Copy Cable Personal Area Ne Human Interface Human Interface Hands Free Profi Advanced Audio I Audio Video Rem Generic Access P Bluetooth LE Ger Device ID Profile HID over GATT Pr Phone Book Acces	cchange Profile ile (OPP) ^{1,1} Replacement (Hetwork User (PA Device (HID) ^{1,1} Device Profile (le (HFP) ^{1.5/1.6} le (HFP) ^{1.5/1.6} Clibitribution Pro- tote Control Pro- tofile (GAP) heric Attribute ((DI) ^{1.3} cofile(HOGP) ^{1.0} ess Profile(PBAF	HCRP) ^{1,0} NU) ^{1.0} Host (HID) ^{1.1} ient ofile (A2DP) ^{1.2} ifile (AVRCP) ^{1.3/1} GATT) Client	.4
	Bluetooth V4.1/V4.2 support Feature	V4.1: ESR5/6/7 c V4.2: ESR8 comp	•	e Connection – B	asic
HP Integrated Module with	Bluetooth® Specification	4.2 Compliant			
Bluetooth®	Frequency Band	2402 to 2480 MF	łz		
4.2 Wireless Technology	Number of Available Channels	Legacy: 0~79 (1	MHz/CH)		
		BLE: 0~39 (2 MHz			
	Data Rates and Throughput	Legacy: 3 Mbps d	lata rate; throu	ghput up to 2.17	7 Mbps
		BLE: 1 Mbps data rate; throughput up to 0.2 Mbps			
		Legacy: Synchronous Connection Oriented links up to 3, 64 voice channels			up to 3, 64 kbps,
		Legacy: Asynchro	onous Connecti	on Less links 21	78.1 kbps/177.1
		kbps asymmetric	: (3-DH5) or 864	4 kbps symmetr	ic (3-EV5)
	Transmit Power	The Bluetooth co device with a ma		-	iss II Bluetooth 3m for BR and EDR
	Receiver Sensitivity	Modulation	0.01% BER	0.001% BER	
		GFSK π/4-DQPSK	-80 dBm -80 dBm	-70 dBm -70 dBm	
		8DPSK	-80 dBm	-70 dBm	
	Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW			
	Antenna	Internally integra	ated within mod	Jule	
	Range	Legacy Up to 33 ft (10 m) BLE Up to 99 ft (30 m)			
	Electrical Interface	USB 2.0 compliar	nt		



Technical Specifications – Networking

Bluetooth® Software Supported	Microsoft Windows Bluetooth Software
Link Topology	Point to Point, Multipoint Pico Nets up to 7 slaves
Security	Full support of Bluetooth Security Provisions
Power Management	Microsoft Windows ACPI, and USB Bus Support
Certifications	Self-configurable to optimize power conservation in all operating modes, including Standby, Hold, Park, and Sniff
Security	All necessary regulatory approvals for supported countries, including:
	FCC (47 CFR) Part 15C, Section 15.247 & 15.249
Power management certificactions	ETS 300 328, ETS 300 826 Low Voltage Directive IEC950 UL, CSA, and CE Mark
Certifications Bluetooth® Profiles Supported	Serial Port Profile (SPP)1 Service Discovery Application Profile (SDAP) Dial-Up Networking (DUN)1,2 Generic Object Exchange Profile (GOEP)1,2 Object Push Profile (OPP)1,2 Hard Copy Cable Replacement (HCRP)1,2 Personal Area Networking Profile (PAN)1,2 Human Interface Device Profile (HID)1,2 Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP) Audio Video Remote Control Profile (AVRCP)
Bluetooth® V4.2 support feature	V4.2: ESR8 compliant, LE Secure Connection – Basic.

- 1. Check latest software/driver release for updates on supported security features.
- 2. Maximum output power may vary by country according to local regulations.
- 3. Receiver sensitivity is measured at a packet error rate of 8% for 802.11b (CCK modulation) and a packet error rate of 10% for 802.11a/g (OFDM modulation).

WLAN supplier's client utility is required for Cisco Compatible Extensions support with Microsoft Windows XP. WLAN may also be compatible with certain third-party software supplicants. WLAN supplier IHV extensions required for Cisco Compatible Extensions support for Microsoft Windows Vista.

Near Field Communications (NFC)

Controller	NFC Mirage WNC XRAV-1 (NXP NPC300 I2C 10mmx17mm)
Supports	 Windows 10 NFC Forum Compliant Near Field Communications Controller
Dimensions (L × W × H)	Module 25 mm by 10 mm by 2.0 mm
Chipset	NPC300
System interface	12C



Technical Specifications – Networking

NFC RF standards	standards ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 156	93 ISO/IEC	
	18092 ECMA-340 NFCIP-1 Target and Initiator ECMA-32	-	
NFC Forum Support Tag	Type 1, Type 2, Type3 and Type 4, NFCIP-1 and NFCIP-2		
Reader	(PCD-VCD) Mode(1) ISO/IEC 14443 A ISO/IEC 14443 B ISO/IEC 15693 MIFARE 1K MIFARE 4K MIFARE DESFire FeliCa Jewel and Topaz cards		
Card Emulation	(PICC-VICC)		
Mode ¹	ISO/IEC 14443 A ISO/IEC 14443 B and B' MIFARE FeliCa		
Frequency	13.56 MHz		
NFC Modes Supported	Reader/Writer, Peer-to-Peer		
Raw RF Data Rates	106, 212, 424, 848 kbps		
Operating temperature	0°C to 70°C		
Storage temperature	-20°C to 125°C		
Humidity	10-90% operating 5-95% non-operating		
Supply Operating voltage	2.97 to 5.5 Volts		
I/O Voltage	1.8V or 3.3V		
Power Consumption	Booster enable VBAT= 3.3V,		
	VCC_BOOST = 5V)Typical 2 Polling 7.3 mA Detected TermMode PowerTotal 283.8 mA Net Module 236.8 mConsumption,Test Tag Type 2 Total 288.8 mA Net241.8 mA Detected Test Tag Type 3mA Net Module 240.7 mA Detected TType 4 Total 282.3 mA Net Module 2	A Detected Module Total 287.7 Fest Tag	
Antenna connector	0.5mm pitch, 7 connector FPC. Antenna matching is external to module.		
Notes	 With application or UICC support Actual Power Consumption is dependent on NFC antenna and matching circuit and on the particular polling sequence and period configured. 		



Technical Specifications – Audio

AUDIO/MULTIMEDIA – BANG & OLUFSEN

Hardware	Implementation	Conexant CX7750		
	Function Key Volume Controls	Volume up, volume down, and mute		
	Line In/Line Out	Yes, via dock		
	Headphone/Microphone in	Yes combo jack		
	Integrated Microphone	Yes, Tri digital microphone array when equipped with optional webcam		
Audio Output Quality	Frequency Response	20 Hz - 20 kHz		
	Signal to Noise Ratio	104 dB		
	Total Harmonic Distortion+noise @-3dBFS	-90dBFS		
	Noise Floor	-110 dB		
	Play/Record Sampling Rate	(s) 8 kHz – 48kHz		
	DAC	192kHz		
	ADC	96kHz		
Integrated Stereo	Power Rating	2 Watts		
Speakers	Impedance	4 Ohms		

Technical Specifications – Power

POWER

HP 65W Smart AC	Dimensions	107.0x47.0x30.0mm	
Adapter	Weight	unit: 250g +/- 10g	
	Input	90 to 265 VAC	
		Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
		Input frequency range	47 to 63 Hz
		Input AC current	Max 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	AC Connector (Ac Inlet)	C6 (3pin/with grounde	d, with Smart ID DC connector)
	AC Connector (Ac Inlet) Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	* Worldwide safety sta SELV; Agency approva FCC Class B, CISPR22 C	ance with LVD and EMC directives andards - IEC60950, EN60950, UL60950, Class1, ls - C-UL-US, NORDICS, DENAN, EN55022 Class B, class B, CCC, NOM-1 NYCE. hours at 25°C ambient condition.
HP 65W Smart	Dimensions	102.0x55.0x30.0mm	
AC Adapter EM	Weight	unit: 350g +/- 10g	
	Input	90 to 265 VAC	
		Input Efficiency	87.0% min at 115 VAC and 230Vac
		Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 VAC
	Output	Output power	Output
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	AC Connector (Ac Inlet)	C6 (3pin/with grounde	d, with Smart ID DC connector)
	AC Connector (Ac Inlet) Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)



Technical Specifications – Power

		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certification	* Worldwide safety sta SELV; Agency approval FCC Class B, CISPR22 C	nce with LVD and EMC directives ndards - IEC60950, EN60950, UL60950, Class1, ls - C-UL-US, NORDICS, DENAN, EN55022 Class B, lass B, CCC, NOM-1 NYCE. hours at 25°C ambient condition.
HP 65W Travel	Dimensions	107.0x47.0x30.0mm	
AC Adapter Argentina	Weight	unit: 250g +/- 10g	
	Input	90 to 265 VAC	
		Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230 Vac
		Input frequency range	47 to 63 Hz
		Input AC current	Max 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	AC Connector (Ac Inlet)	C6 (3pin/with grounded, with Smart ID DC connector)	
	AC Connector (Ac Inlet) Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	* Worldwide safety standa SELV; Agency approvals - (Class B, CISPR22 Class B, C	with LVD and EMC directives Irds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC CC, NOM-1 NYCE. Irs at 25°C ambient condition.

HP 65W Smart
USB Type C Adapter

Dimensions Weight Input 74x74x28.5mm unit: 245g +/- 10g **Input Efficiency**

81.5% min at 115 Vac/ 230Vac @ 5V/3A 86.7% min at 115 Vac/ 230Vac @ 9V/3A 88% min at 115 Vac/ 230Vac @ 10V/5A 88% min at 115 Vac/ 230Vac @ 12V/5A 89% min at 115 Vac/ 230Vac @ 15V/4.33A



89% min at 115 Vac/ 230Vac @ 20V/3.25A

		Input frequency range	47 to 63 Hz
		Input AC current	Max 1.7 A at 90 Vac
	Output	Output power	65W
		DC output	5V/9V/10V/12V/15V/20V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<8.0A
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	*Worldwide safety standar SELV; Agency approvals - C Class B, CISPR22 Class B, C	with LVD and EMC directives ds - IEC60950, EN60950, UL60950, Class1, -UL-US, NORDICS, DENAN, EN55022 Class B, FCC CC, NOM-1 NYCE. rs at 25°C ambient condition.
HP 65W Travel	Dimensions	120.0x57.6x16.7mm	
AC Adapter	Weight	unit: 250g +/- 10g	
	Input	Input Efficiency	88.0 % at 115 Vac and 89.0 % at 230Vac
	•	Input frequency range	47 to 63 Hz
		Input AC current	1.7 A at 90 Vac
	Output	Output power	65W
		DC output	19.5V/5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<11.0A
	DC Plug	4.5mm/7.4mm tips	
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	* Worldwide safety standa SELV; Agency approvals - C Class B, CISPR22 Class B, C	with LVD and EMC directives rds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC CC, NOM-1 NYCE. rs at 25°C ambient condition.
HP 45W Smart	Dimensions	3.74 x 1.57 x 1.04 in (9.5 x	4.0 x 2.65 cm)
AC Right Angle Adapter	Weight	0.386 lb (175g) max	



•			
	Input	Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range	47 to 63 Hz
		Input AC current	Max 1.4 A at 90 VAC
	Output	Output power	45W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<8.0 A
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	* Worldwide safety standa SELV; Agency approvals - Class B, CISPR22 Class B, C	with LVD and EMC directives ards - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC CCC, NOM-1 NYCE. urs at 25°C ambient condition.
HP 45W Smart	Dimensions (H × W × D)	95.0x40.0x26.5mm	
AC Adapter (2 Prong)	Weight	unit: 200g +/- 10g	
	Input	90 to 265 VAC	
		Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
		Input frequency range	47 to 63 Hz
		Input AC current	Max. 1.4 A at 90 Vac
	Output	Output power	45W
		DC output	19.5V
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<8.0A
	AC Connector (Ac Inlet)	C8 (2 pin/non-grounded, v	vith Smart ID DC connector)
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	20% to 95%
		Storage Humidity	10% to 95%
	EMI and Safety Certifications	* Worldwide safety standa SELV; Agency approvals - Class B, CISPR22 Class B, C	with LVD and EMC directives ards - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC CCC, NOM-1 NYCE. urs at 25°C ambient condition.
HP 45W Smart	Dimensions	3.74 x 1.57 x 1.04 in (9.5 x	2 4 0 x 2 65 cm)
AC Right Angle Adapter	Dimensions Weight	0.386 lb (175g) max	
Argentina	-	Input Efficiency	87.74% at 115Vac and 88.4% at 230Vac
	Input	mput Entitienty	01.1470 at 113 vat allu 00.470 dl 230 Vat



		Input frequency range	47 to 63 Hz
		Input AC current	Max 1.4 A at 90 VAC
	Output	Output power	45W
	σαιμαί	DC output	45W 19.5V
		Hold-up time	
		•	5 ms at 115 Vac input
	Environmental Design	Output current limit	<8.0 A
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	*Worldwide safety standar SELV; Agency approvals - (Class B, CISPR22 Class B, C	with LVD and EMC directives rds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC CC, NOM-1 NYCE. rs at 25°C ambient condition.
HP 45W Smart	Dimensions	62.0x62.0x28.5mm	
USB Type C Adapter	Weight	unit: 220g +/- 10g	
	Input	Input Efficiency	Average Efficiency of 25%, 50%, 75%, 100% load condition with 115Vac/230Vac Spec: 5V : 81.5% 9V : 86.7% 10V : 87.5% 12V : 87.8% 15V : 87.8% 20V : 87.8%
		Input frequency range	47 to 63 Hz
		Input AC current	Max 1.4 A at 90 Vac
	Output	Output power	45W
		DC output	5V/15W; 9V/27W; 10V/37.5W; 12V/45W; 15V/45W; 20V/45W
		Hold-up time	5 ms at 115 Vac input
		Output current limit	<5.0A
	Environmental Design	Operating temperature	32° to 95° F (0° to 35° C)
		Non-operating (storage) temperature	-4° to 185° F (-20° to 85° C)
		Altitude	0 to 16,400 ft (0 to 5,000 m)
		Humidity	5% to 95%
		Storage Humidity	5% to 95%
	EMI and Safety Certifications	* Worldwide safety standa SELV; Agency approvals - (Class B, CISPR22 Class B, C	with LVD and EMC directives rds - IEC60950, EN60950, UL60950, Class1, C-UL-US, NORDICS, DENAN, EN55022 Class B, FCC CC, NOM-1 NYCE. Irs at 25°C ambient condition.



HP Long Life 3-cell Polymer Battery (56WHr)	Dimensions (H x W x L) Weight Cells/Type	7.15mm x 79.65mm x 281.7mm 219 g +/- 10g 3cell Lithium-Ion Polymer cell / P615383A1	
	Energy	Voltage	11.55V
	Temperature	Amp-hour capacity Watt-hour capacity Operating (Charging)	4.610Ah/4.850Ah 56whr 32° to 122° F (0° to 50° C)
	Fuel Gauge LED Warranty	Operating (Discharging) No 3-year	14° to 140° F (-10° to 60° C)
	Optional Travel Battery Available	No	



ENVIRONMENTAL DATA

Eco-Label Certifications & declarations System Configuration	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] EPEAT[™] Gold registered in the United States. See http://www.epeat.net for registration status in your country. Search keyword <i>generator</i> on HP's 3rd party option store for solar energy accessory at http://www.hp.com/go/options. The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook". 		
Energy Consumption (in accordance with US ENERGY STAR® test method) Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off	115VAC, 60Hz 9.06 W 7.31 W 0.76 W 0.44 W	230VAC, 50Hz 9.98 W 7.82 W 0.89 W 0.56 W	100VAC, 60Hz 9.6 W 8.0 W 0.75 W 0.43 W
	Note: Energy efficiency data listed is for a model family. HP computers marke applicable U.S. Environmental Prote computers. If a model family does r energy efficiency data listed is for a efficiency power supply, and a Micro	d with the ENERGY STAR ection Agency (EPA) ENER tot offer ENERGY STAR® c typically configured PC f	Dogo are compliant with the RGY STAR [®] specifications for compliant configurations, then eaturing a hard disk drive, a high
Heat Dissipation* Normal Operation (Short idle) Normal Operation (Long idle) Sleep Off	115VAC, 60Hz 31 BTU/hr 25 BTU/hr 3 BTU/hr 2 BTU/hr *NOTE: Heat dissipation is calculate	230VAC, 50Hz 34 BTU/hr 27 BTU/hr 3 BTU/hr 2 BTU/hr d based on the measured	100VAC, 60Hz 33 BTU/hr 27 BTU/hr 3 BTU/hr 1 BTU/hr d watts, assuming the service
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296) Typically Configured – Idle Fixed Disk – Random writes Longevity and Upgrading	level is attained for one hour. Sound Power (L _{WAd} , bels) 2.9 2.9 This product can be upgraded, poss Upgradeable features and/or comp 3 USB ports 1 PC card slot (type I/II) 1 ExpressCard/54 slot 1 IEEE 1394 Port 2 SODIMM memory slots 0 Optional expansion base docking 1 multi-bay II storage port Interchangeable HDD??	onents contained in the p	

(III)

	Spare parts are available throughout the end of production.	he warranty period and or for up to "5" years after the
Batteries	This battery(s) in this product comply w	with EU Directive 2006/66/EC
	Batteries used in the product do not co Mercury greater the1ppm by weigh Cadmium greater than 20ppm by w	ht
	Battery description: CR2032 (coin cell) Battery type: Lithium	
Additional Information	 directive - 2011/65/EC. This HP product is designed to Equipment (WEEE) Directive – This product is in compliance v Drinking Water and Toxic Enfo This product is in compliance v see www.epeat.net Plastics parts weighing over 22 and ISO1043. This product contains 9.0% po 	with California Proposition 65 (State of California; Safe
Packaging Materials	External: PAPER/Corrugated	345 g
Material Usage		ne - PP 76 g e low density - LDPE 15 g ns at least 50% recycled content. erials contains at least 70% recycled content. he following substances in excess of regulatory limits for the Environment at
	plastics Cadmium Chlorinated Hydrocarbons Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methan Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries	used on the external surface designed to be frequently r. BBs)

	 Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	Hewlett-Packard offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental Information	For more information about HP's commitment to the environment: Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_De sign_ISO_14K_Certificate.pdf and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
Country of Origin	

China



Туре	Description	Part #
Memory	HP 4GB DDR4-2400 SODIMM (Core processors only)	Z4Y84AA
	HP 16GB DDR4-2400 SODIMM (Core processors only)	Z4Y86AA
Cases	HP 15.6 Business Top Load– Refresh	2SC66AA
	HP USB-C Universal Dock	1MK33AA#xxx
Docking	HP USB-C Mini Dock	1PM64AA#xxx
	HP USB-C Universal Dock w/4.5mm Adapter	2UF95AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock 120W G2 TAA	2UK37AA
Input/Output -	HP TB Dock G2 w/Combo Cable	3TR87AA#xxx
Mice	HP TB Docks 120W G2 w/Audio	3YE87AA#xxx
	HP Ultra Slim Docking Station	D9Y32AA#xxx
	HP Travel Hub	ТОКЗОАА
	HP Comfort Grip Mouse	H2L63AA
	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP USB Travel Mouse	G1K28AA#xxx
Battery	HP Slim Wireless Keyboard and Mouse	T6L04AA#xxx
Adapters	HP Slim USB Keyboard and Mouse	ТбТ8ЗАА
	HP Wireless (Link-5) Keyboard	T6U20AA#xxx
	HP 65W Smart AC Adapter	H6Y89AA
	HP 90W Smart AC Adapter	H6Y90AA
	HP 150W Slim Smart AC Adapter	TBD
	HP TA03XL Rechargeable Battery	1FN06AA
	HP USB-C™ to VGA Adapter	N9K76AA
	HP USB-C to USB Hub	Z6A00AA
	HP HDMI to DVI adapter	F5A28AA
	DisplayPort™ to DVI Adapter	F7W96AA
	DisplayPort™ to VGA	F7W97AA
	DisplayPort™ to HDMI 1.4 Adapter	F3W43AA
	HP lt4120 LTE/EVDO/HSPA+ Gobi™ 4G Mobile Broadband Module	TBD
Collaboration	HP UC Conferencing Keyboard	K8P74AA#xxx
Wireless Collaboration	HP USB Collaboration Keyboard	Z9N38AA
	HP Stereo 3.5mm Headset	T1A66AA
	HP Stereo USB Headset	T1A67AA
Storage -	HP External USB DVDRW Drive	F2B56AA
External	HP 500GB 7200rpm HDD	F3B97AA
Storage	HP External USB DVDRW Drive	F2B56AA
	HP 500GB 7200rpm HDD	F3B97AA
	HP 256GB M2 NVME PCIe SSD (2280)	V3K66AA
	HP 512GB M2 NVME PCIe SSD (2280)	V3K67AA
	HP Dual Head Cable Lock (Non-Master key)	T1A64AA
Security	HP Dual Head Cable Lock (Master Key)	T1A65AA



Options and Accessories (sold separately and availability may vary by country)

Memory	HP 15.6" Notebook PC Privacy Filter (non-touch)	J7H71AA
•	HP Docking Station Cable Lock	AU656AA#XXX
	HP Essential Combination Lock	TOY16AA
	HP Combination Lock	TOY15AA
	HP Keyed Cable Lock	TOY14AA
	HP 15'6 Privacy Filter (touch panel)	V8Z58AA#xxx
	HP 4GB DDR4-2400 SODIMM (Core processors only)	Z4Y84AA
	HP 16GB DDR4-2400 SODIMM (Core processors only)	Z4Y86AA
	HP 15.6 Business Top Load– Refresh	2SC66AA
Cases	HP USB-C Universal Dock	1MK33AA#xxx
Docking	HP USB-C Mini Dock	1PM64AA#xxx
	HP USB-C Universal Dock w/4.5mm Adapter	2UF95AA
	HP Thunderbolt Dock 120W G2	2UK37AA
	HP Thunderbolt Dock 120W G2 TAA	2UK37AA
	HP TB Dock G2 w/Combo Cable	3TR87AA#xxx
Input/Output -	HP TB Docks 120W G2 w/Audio	3YE87AA#xxx
Mice	HP Ultra Slim Docking Station	D9Y32AA#xxx
	HP Travel Hub	ТОКЗОАА
	HP Comfort Grip Mouse	H2L63AA
	HP 3-Button Laser Mouse	H4B81AA#xxx
	HP X4000 Bluetooth Mouse	H3T50AA#xxx
	HP Slim Bluetooth Mouse	F3J92AA#xxx
	HP USB Travel Mouse	G1K28AA#xxx
	HP Slim Wireless Keyboard and Mouse	T6L04AA#xxx
	HP Slim USB Keyboard and Mouse	ТбТ8ЗАА
	HP Wireless (Link-5) Keyboard	T6U20AA#xxx
	HP 65W Smart AC Adapter	H6Y89AA
	HP 90W Smart AC Adapter	H6Y90AA
Battery	HP 150W Slim Smart AC Adapter	TBD
Adapters	HP TA03XL Rechargeable Battery	1FN06AA
	HP USB-C™ to VGA Adapter	N9K76AA
	HP USB-C to USB Hub	Z6A00AA
	HP HDMI to DVI adapter	F5A28AA
	DisplayPort [™] to DVI Adapter	F7W96AA
	(for 1 year platforms)	UC282E
Care Packs	(for 3 year platforms)	UC279E
	(for 3 year platforms)	UC279E
NOTE: External p	ower supplies, power cords, cables and peripherals are not low halogen. Serv	ice parts obtained after purchase

NOTE: External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.



Summary of Changes

Date of change:	Version History:		Description of change:	
February 15, 2018	From v1 to v2	Changed	Environmental data updated	
February 23, 2018	From v2 to v3	Added	Dock, case, mouse, adapter, display and care packs added to options section	
March 1, 2018	From v3 to v4	Added	Battery note on power supply section	
May 24, 2018	From v4 to v5	Changed	Format	
August 20, 2018	From v5 to v6	Changed	General update	
August 27, 2018	From v6 to v7	Changed	Format	
October 17, 2018	From v7 to v8	Changed	Format	
November 26, 2018	From v8 to v9	Changed	Multi-display section	



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